



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Introduction

| DESCRIPTION | KEY FEATURES |
|---|---|
| <p>Microsemi's PD69101 is a single port, mixed-signal, high-voltage Power over Ethernet driver. The device is utilized in Ethernet switches and enables network devices to share power and data over the same cable. It enables detection of IEEE802.3af-2003 compliant PDs (Powered Devices) and IEEE802.3at High Power Devices, thus, ensuring safe power feeding and disconnection of ports with full digital control and a minimum of external components. Integrating power, analog and state of the art logic, the PD69101 device fits into a single 24-pin, plastic QFN package.</p> <p>A "plug and play" device, the PD69101 executes all real time functions as specified in the IEEE802.3af-2003 ("AF") and IEEE802.3at High Power ("AT") standards, including load detection, "AF" and "AT" classification, and using Multiple Classification Attempts (MCA).</p> <p>The PD69101 :</p> <ul style="list-style-type: none"> Is designed to detect and disable disconnected ports, utilizing DC disconnection methods, as specified in the IEEE 802.3af-2003 and IEEE802.3ar-2009 standards. Can optionally detect legacy/pre-standard PD devices. Provides PD protection such as over-load, under-load, over-voltage, over-temperature and short-circuiting. Supports supply voltages ranging from 44 V to 57 VDC with no need for additional power supply sources. Is a low power device using an internal 0.34 Ω MOSFET and an external 0.5 Ω sense resistor. <p>The chip includes built-in internal thermal protection.</p> <p>Two LEDs provide port state's indication and port type (AF/AT).</p> | <ul style="list-style-type: none"> Fully IEEE802.3af-2003 and IEEE802.3at-2009 compliant Includes two-event classification Supports pre-standard PD detection Supports Cisco devices detection Single DC voltage input (44 - 57 VDC) Supports 2 Pairs and 4 Pairs (Data and Spare Power Feeding) V_{MAIN} Out of Range Protection Wide temperature range: -40° to +85° C Over-temperature protection Low thermal dissipation (0.5 Ω sense resistor) Includes on/off command pin 2 x direct LEDs drive Continuous port monitoring and system data Configurable load current setting Configurable AT/AF modes Configurable standard and legacy detection mode Power soft start mechanism On-chip thermal protection Voltage monitoring & protection Built in 3.3 VDC regulator Internal power on reset RoHS compliant Low Rdson FET: 0.3 Ω |
| <p>IMPORTANT: For the most current data, consult MICROSEMI's website: http://www.microsemi.com</p> | |

| PACKAGE ORDER INFO | | THERMAL DATA |
|---------------------------|---------------------------------|---|
| T_A (°C) | Plastic 24 pin QFN 4x5 | TYPICAL THERMAL RESISTANCE-JUNCTION TO AMBIENT 25° C/W |
| | RoHS Compliant / Pb-free / MSL1 | TYPICAL THERMAL RESISTANCE-JUNCTION TO CASE 4° C/W |
| -40 to +85 | PD69101ILQ-TR | Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$. The θ_{JA} numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow. |

ROHS AND SOLDER REFLOW INFORMATION

RoHS 6/6

Pb-free 100% Matte Tin Finish

Package Peak Temperature for Solder Reflow 260° C (+0° C, -5° C)
 (40 seconds maximum exposure)

Notes: Exceeding these ratings can damage the device.

IPC/JEDEC J-STD-020C

July 2004

Table 5-2 Classification Reflow Profiles

| Profile Feature | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
|---|-------------------------|------------------|
| Average Ramp-Up Rate (T _{Smax} to T _p) | 3 °C/second max. | 3° C/second max. |
| Preheat | | |
| – Temperature Min (T _{Smin}) | 100 °C | 150 °C |
| – Temperature Max (T _{Smax}) | 150 °C | 200 °C |
| – Time (t _{Smin} to t _{Smax}) | 60-120 seconds | 60-180 seconds |
| Time maintained above: | | |
| – Temperature (T _L) | 183 °C | 217 °C |
| – Time (t _L) | 60-150 seconds | 60-150 seconds |
| Peak/Classification Temperature (T _p) | See Table 4.1 | See Table 4.2 |
| Time within 5 °C of actual Peak Temperature (t _p) | 10-30 seconds | 20-40 seconds |
| Ramp-Down Rate | 6 °C/second max. | 6 °C/second max. |
| Time 25 °C to Peak Temperature | 6 minutes max. | 8 minutes max. |

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

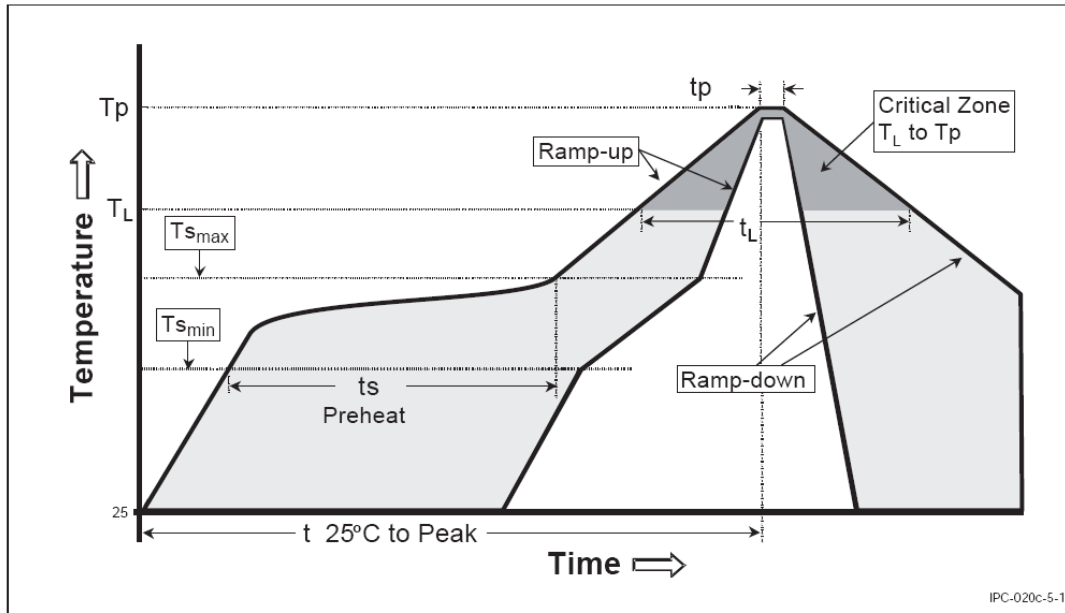


Figure 5-1 Classification Reflow Profile

Table 4-2 Pb-free Process – Package Classification Reflow Temperatures

| Package Thickness | Volume mm ³ <350 | Volume mm ³ 350 - 2000 | Volume mm ³ >2000 |
|-------------------|-----------------------------|-----------------------------------|------------------------------|
| <1.6 mm | 260 +0 °C * | 260 +0 °C * | 260 +0 °C * |
| 1.6 mm - 2.5 mm | 260 +0 °C * | 250 +0 °C * | 245 +0 °C * |
| ≥2.5 mm | 250 +0 °C * | 245 +0 °C * | 245 +0 °C * |

* Tolerance: The device manufacturer/supplier shall assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0 °C. For example 260 °C+0°C) at the rated MSL level.

Electrical Characteristics

Unless otherwise specified, the following specifications apply to the operating ambient temperature, T_{AMB} -40° to +85° C.

| PARAMETER | SYMBOL | TEST CONDITIONS / COMMENT | PD69101 CONTROLLER | | | UNIT |
|---------------------------------------|---|---|--------------------|-----|------|-------------|
| | | | MIN | TYP | MAX | |
| POWER SUPPLY | | | | | | |
| Input Voltage | V_{MAIN} | Supports Full IEEE802.3 functionality | 44 | 55 | 57 | VDC |
| Power Supply Current @ Operating Mode | | $V_{MAIN} = 55 V$ | | | 10 | mA |
| DIGITAL I/O | | | | | | |
| Input Logic High Threshold | V_{IH} | | 2.2 | | | VDC |
| Input Logic Low Threshold | V_{IL} | | | | 0.8 | VDC |
| Input Hysteresis Voltage | | | 0.4 | 0.6 | 0.8 | VDC |
| Input High Current | I_{IH} | | -10 | | 10 | uA |
| Input Low Current | I_{IL} | | -10 | | 10 | uA |
| Output High Voltage | V_{OH} | For $I_{OH} = -1 mA$ | 2.4 | | | VDC |
| Output Low Voltage | V_{OL} | $I_{OH} = 1 mA$ | | | 0.4 | VDC |
| POE LOAD CURRENTS | | | | | | |
| AT High Limit Mode | AT_LIM_HIGH (high current level for future use) | $R_{SENSE} = 0.5 \Omega$ 1% connected at Port_Sense pin | 1.18 | 1.2 | 1.28 | A |
| AT Medium Limit Mode | AT_LIM_MID (medium current level for future use) | | 847 | 874 | 919 | mA |
| AT Low Limit Mode | AT_LIM_LOW | | 706 | 722 | 767 | mA |
| AF Limit Mode | AF_LIM | | 410 | 425 | 448 | mA |
| MAIN POWER SWITCHING FET | | | | | | |
| On Resistance | R_{DSON} | | | 0.3 | | Ω |
| Internal Thermal Protection Threshold | | | | 200 | | $^{\circ}C$ |
| LED0 AND LED1 DRIVERS | | | | | | |
| Current Sink | I sink (from Vmain to AGND) | | | 3 | 5 | mA |

Dynamic Characteristics

The PD69101 utilizes three current level thresholds (I_{min} , I_{cut} , I_{lim}) and three timers (T_{min} , T_{cut} , T_{lim}).

- Loads that consume I_{lim} current for more than T_{lim} are labeled as 'short circuit state' and shutdown.
- Loads that dissipate more than I_{cut} for longer than T_{cut} are labeled as 'overloads' and are shutdown.
- If output power is below I_{min} for more than T_{min} , the PD is labeled as 'no-load' and is shutdown.

Automatic recovery from over-load and no-load conditions is attempted every T_{OVLREC} periods (typically 1 second). Output power is limited to I_{lim} , which is a maximum peak current allowed at the port.

Table 1: IEEE802.3 AF Mode Parameters

| PARAMETER | CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|--|--|--|------|------|------|------|
| Automatic Recovery from No-load Shutdown | T_{UDLREC} value, measured from port shutdown point (can be modified through control port) | | | 1 | | Sec |
| Cutoff timers Accuracy | Typical accuracy of T_{cut} | | | 2 | | ms |
| Inrush Current | I_{Inrsh} | For $t=50$ ms, $C_{load}=180$ uF max. | 400 | | 450 | mA |
| Output Current Operating Range | I_{port} | Continuous operation after startup period. | 10 | | 375 | mA |
| Output Power Available Operating Range | P_{port} | Continuous operation after startup period, at port output. | 0.57 | | 15.4 | W |
| Off mode Current | I_{min1} | Must disconnect for T greater than T_{UVL} | 0 | | 5 | mA |
| | I_{min2} | May or may not disconnect where T is greater than T_{UVL} | 5 | 7.5 | 10 | mA |
| PD Power Maintenance Request Drop-out Time Limit | T_{PMDO} | Buffer period to handle transitions | 300 | | 400 | ms |
| Over-load Current Detection Range | I_{cut} | Time limited to T_{OVL} | 350 | | 400 | mA |
| Over Load Time Limit | T_{OVL} | | 50 | | 75 | ms |
| Turn On Rise Time | T_{rise} | From 10% to 90% of V_{port} (Specified for PD load consisting of 100 uF capacitor in parallel to 200 Ω). | 15 | | | us |
| Turn Off Time | T_{off} | From V_{port} to 2.8 Vdc | | | 500 | ms |
| Time Maintain Power Signature | T_{MPS} | DC modulation time for DC disconnect | | 49 | | ms |

Table 2: IEEE802.3 AT Mode Parameters

| PARAMETER | CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|--|---|---|------|------|-------|------|
| Automatic Recovery from No-load Shutdown | T _{UDLREC} value; measured from port shutdown point (can be modified through control port) | | | 1 | | s |
| Cutoff Timers Accuracy | Typical accuracy of T _{cut} | | | 2 | | ms |
| Inrush Current | I _{Inrsh} | For t = 50 ms, Cload = 180 uF max. | 400 | | 450 | mA |
| Output Current Operating range | I _{port} | Continuous operation after startup period | 10 | | 725 | mA |
| Output Power Available, Operating Range | P _{port} | Continuous operation after startup period at port output | 0.57 | | 36.25 | W |
| Off Mode Current | I _{min1} | Must disconnect where T is greater than T _{UVL} | 0 | | 5 | mA |
| | I _{min2} | May or may not disconnect where T is greater than T _{UVL} | 5 | 7.5 | 10 | mA |
| PD Power Maintenance request drop-out time limit | T _{PMDO} | Buffer period to handle transitions | 300 | | 400 | ms |
| Over-load Current detection range | I _{cut} | Time limited to T _{OVL} | | | 600 | mA |
| Over-load Time Limit | T _{OVL} | | 50 | | 75 | ms |
| Turn on Rise Time | T _{rise} | From 10% to 90% of V _{port} (Specified for PD load consisting of 100 uF capacitor in parallel to 200 Ω). | 15 | | | us |
| Turn Off Time | T _{off} | From V _{port} to 2.8 Vdc | | | 500 | ms |
| Time Maintain Power Signature | TMPS | DC modulation time for DC disconnect | | 49 | | ms |

Detailed Pinout Description

| PIN | PIN NAME | PIN TYPE | DESCRIPTION |
|-----|--------------|----------------|--|
| 0 | Exposed PAD | Analog Gnd | Exposed PAD; metal plate on the IC bottom side connected to analog ground. A high quality ground plane (about 500 mil inch over 500 mil inch) should be deployed around this pin whenever possible. |
| 1 | CURRENT_SET | Digital Input | User input to set AF / AT and maximum current limit. Use Pull-up resistors to DVDD or Pull-Down resistors to DGND to set mode of operation according to the detailed tables (page 4). |
| 2 | AF/AT | Digital Input | |
| 3 | DVDD | Power In | Regulated Input Voltage (3.3 V) for internal digital circuitry. Should be externally connected to pin 4. |
| 4 | VAUX3P3 | Power In | Voltage regulation in 3.3 VDC. To be connected to pin 5. A 4.7 uF capacitor to AGND is recommended. |
| 5 | DRV_VAUX3P3 | Power Out | Internal voltage regulator out 3.3 VDC. To be connected externally to pin 4. |
| 6 | VAUX5 | Power | Regulated 5 VDC voltage filter. A 1 uF capacitor to AGND is recommended. |
| 7 | AGND | Power | Analog GND |
| 8 | V_MAIN | Power | Supply voltage for the internal analog circuit. Place a low ESR bypass capacitor, not less than 1 uF, as close as possible to AGND and this pin with low impedance traces. |
| 9 | PORT_NEG | Analog I/O | Negative output of the port. |
| 10 | PORT_SENSE | Analog Input | Sense resistor port input (connected to 0.5, 1% Ohm resistor to GND). |
| 11 | QGND | Power | Quiet analog ground: used for sensitive analog cells. |
| 12 | I_REF | Analog I/O | Resistor reference. Connect 30.1 K 1% resistor to QGND. |
| 13 | LED0 | Open Drain I/O | Port Status Direct LED indications – see detailed table description. This is a High voltage, Open drain, Active low (SINK) output pin. Recommended to be connected to LED and Vmain through a ~18.2 Kohm (~3 mA) resistor |
| 14 | LED1 | Open Drain I/O | |
| 15 | N/C | Analog I/O | Test pin; for production use only. Keep open; not connected. |
| 16 | N/C | Analog I/O | |
| 17 | TRIM | Analog Input | Zapping Input for IC production trimming. Should be connected to DVDD. |
| 18 | SYNC | Digital I/O | Synchronization open drain IO pin between master and slave, for 4-Pair applications In ALT A 2 Pair mode (Switch) this pin should be pulled down to DGND via a 4.7 Kohm resistor. In 4 Pair mode, connect the SYNC pin of Master and Slave and pull it up to the DVDD with 4.7 Kohm resistor |
| 19 | DGND | Digital I/O | Digital GND. |
| 20 | RESET_N | Digital Input | Reset input / On-Off command (Active Low). |
| 21 | MODE 0 | Test I/O | Configuration Input Pins: Used to set Mode of operation and Test mode at production. Typically connected to DGND. See Table Below |
| 22 | MODE 1 | Test I/O | |
| 23 | Master/Slave | Digital Input | If connected to DVDD (3.3 VDC): Master mode If connected to GND: Slave mode (4 Pair application) |

| PIN | PIN NAME | PIN TYPE | DESCRIPTION |
|-----|------------------|---------------|---|
| 24 | STD_DET / LEGACY | Digital Input | User input pin to set chip mode of operation. <ul style="list-style-type: none"> “1”: DVDD = IEEE802.3af compliant resistor detection only “0”: DGND = AF / AT Detection and Legacy (non-standard) line detection |

Additional Pin Description and Notes

Note:

- “0” = Connect to DGND
- “1” = Connect to DVDD

CURRENT_SET and **AF/AT** pins determine the typical PD Load output current as detailed in the following coding:

| AT/AF PIN | CURRENT_SET PIN | CONTINUE MAX CURRENT I CUT [MA] | TYPICAL I LIM [MA] | IEEE802.3 |
|-----------|-----------------|---------------------------------|--------------------|----------------------------|
| 0 | 0 | 350 | 425 | AF mode (standard) |
| 1 | 0 | 600 | 722 | AT mode (standard) |
| 1 | 1 | 720 | 874 | AT mode (high power) |
| 0 | 1 | 1000 | 1200 | AT mode (extra high power) |

Configuration / Mode of Operation Coding:

| MODE 0 | MODE 1 | MODE | DESCRIPTION |
|--------|--------|------------------------|--|
| 0 | 0 | Normal operation Mode | Standard Operation POE Mode – LED0 and LED1 Outputs are used for Direct LED Drive as listed below |
| 0 | 1 | Serial Monitoring Mode | Standard Operation POE Mode – LED0 and LED1 are used to Continuously Streaming Out Internal Logic Signals for POE Monitoring |
| 1 | 0 | Test Logic Mode | Internal IC Logic Test Mode – Used in production only |
| 1 | 1 | JTAG Mode | Internal IC Logic Test Mode – Used in production only |

LED I/Os Behavior

- LED pin is a high voltage Open Drain output pin.
- LED pin is an Active Low (SINK) pin → LED is “ON” when I/O is pulled Low.

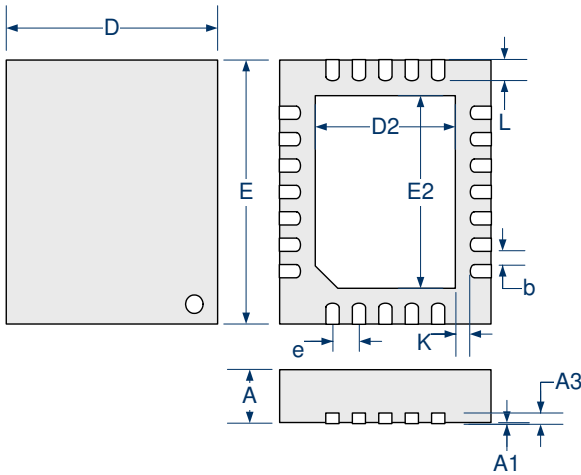
Table 3: 2 Pair Behavior

| STATUS INDICATIONS | LED0 | LED1 | NOTES |
|---|-------------|-------------|---|
| AF Mode – Port “ON” | ON | OFF | Useful for Bicolor LED connected from LED0 to LED1 |
| AT Mode (Class AT was detected) - Port “ON” | ON | ON | |
| AF Mode – Over-load or short | Blink 1 Hz | OFF | Blinking continues for ~ 2 sec |
| AT Mode – Over-load or short | Blink 1 Hz | Blink 1 Hz | Blinking continues for ~ 2 sec |
| Vmain Voltage out of range or IC over-temperature | Blink 4 Hz | OFF | Blinking continues as long as over-voltage or over-temperature state exists |
| AF Mode – Port “OFF” | OFF | ON | Useful for Bicolor LED connected from LED0 to LED1 |
| AT Mode – Port “OFF” | OFF | OFF | |

Table 4: 4 Pair Behavior (2 x PD69101 ICs)

| STATUS INDICATIONS | LED0 | LED1 | NOTES |
|--|------------------|-------------|---|
| Master IC “ON and Slave IC “ON” | OFF | ON | |
| Only Master IC “ON (Slave IC “OFF”) | ON | OFF | |
| Master and Slave ICs are both “OFF” due to Overload or Short | OFF | Blink 1 Hz | Blinking continues for ~ 2 sec after overload / short event |
| Vmain Voltage out of range or IC over-temperature | Blink 4 Hz / 1Hz | OFF | Master IC fail: blink 4 Hz Slave IC fail: blink 1 Hz Blinking continues for ~ 2 sec |
| Master IC “OFF” and Slave IC “OFF” | OFF | OFF | |

PD69101 - Package Description

LQ 24-Pin QFN 4x5mm


| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.80 | 1.00 | 0.031 | 0.039 |
| A1 | 0.00 | 0.05 | 0 | 0.002 |
| A3 | 0.20 REF | | 0.008 REF | |
| K | 0.20 MIN | | 0.008 MIN | |
| e | 0.50 BSC | | 0.02 BSC | |
| L | 0.30 | 0.50 | 0.012 | 0.02 |
| b | 0.18 | 0.30 | 0.007 | 0.012 |
| D2 | 2.50 | 2.75 | 0.098 | 0.108 |
| E2 | 3.50 | 3.75 | 0.138 | 0.148 |
| D | 4.00 BSC | | 0.158 BSC | |
| E | 5.00 BSC | | 0.197 BSC | |

Note:

Dimensions do not include protrusions; these shall not exceed 0.155mm (.006") on any side. Lead dimension shall not include solder coverage.

PD69101 - Internal Block Diagram

The PD69101 is based on two major sections (see Figure 1):

1. A Digital section which controls and monitors the logical PoE functions (state machines, timings etc.)
2. An Analog section which performs the Front End analog PoE functionality.

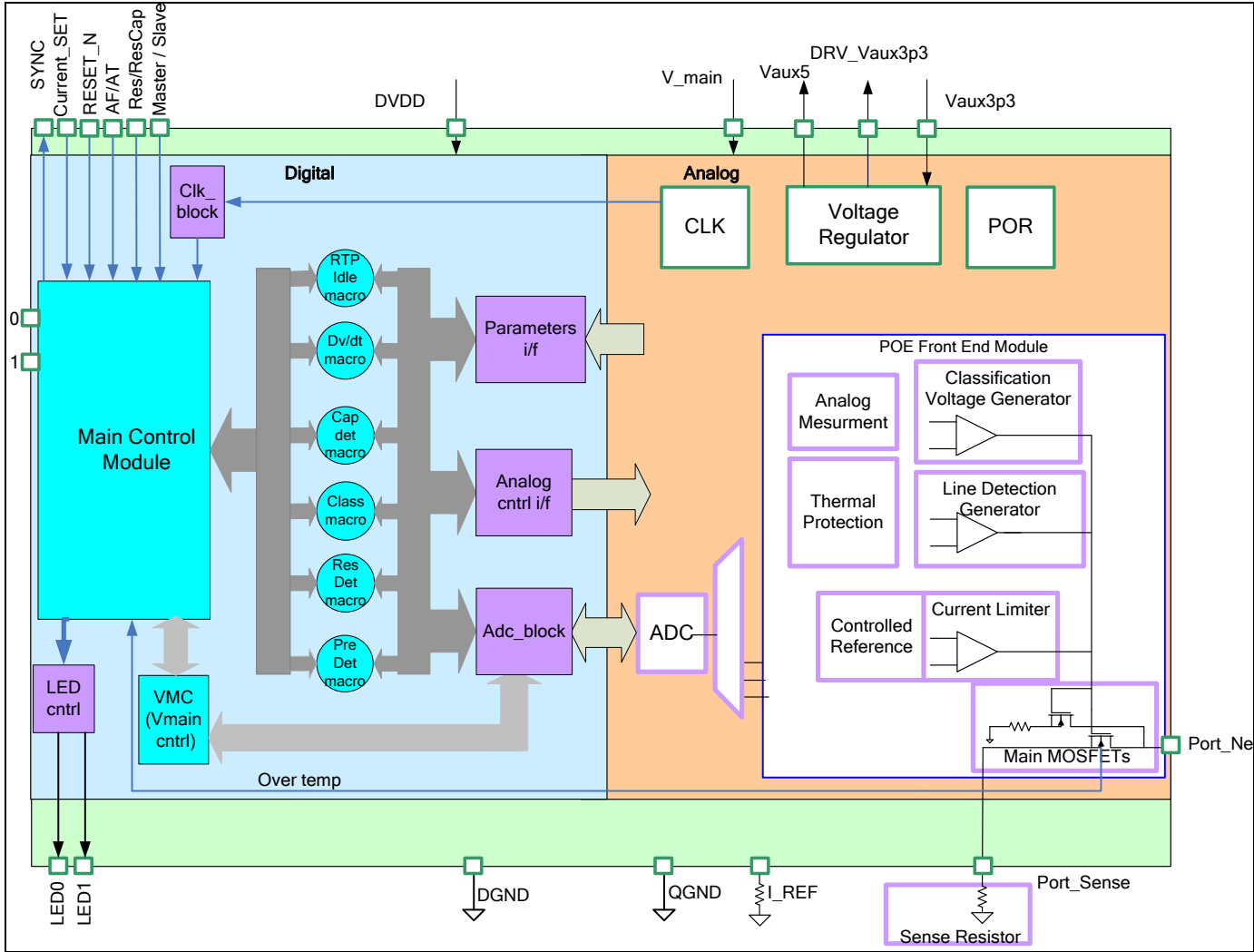


Figure 1: PD69101 Internal Block Diagram

Logic Main Control Module

The Logic Main Control Block includes the Digital Timing Mechanisms and State Machines, synchronizing and activating the PoE functions such as:

- Real Time Protection (RTP)
- Start Up Macro (DVDT)
- Load Signature Detection (RES DET)
- Classification Macro (CLASS)
- Voltage and Current Monitoring Registers (VMC)
- LEDs Stream Out Control Indications
- ADC Interfacing
- Direct Digital Signals with Analog Block

Line Detection Generator

Upon request from the Main Control Module, four different voltage levels are generated by the Line Detection Generator, ensuring robust AF / AT Line Detection functionality.

Classification Generator

Upon request from the Main Control Module, the State Machine applies a regulated Class Event and Mark Event voltages to the ports, as required by the IEEE standard.

Current Limiter

This circuit continuously monitors the current of powered ports and limits the current to a specific value, according to pre-defined limits as set by AF/AT and Current_Set pins. In cases where the current exceeds this specific level, the system starts measuring the elapsed time. If this time period is greater than a preset threshold, the port is disconnected.

Main MOSFET

Main power switching FET, used to control PoE current into the load.

ADC

A 10-Bit Analog to Digital converter, used to convert analog signals into digital registers for the Logic Control module.

Power on Reset (POR)

This circuit monitors the internal 3.3 V voltage DC levels. If this voltage drops below specific thresholds, a reset signal is generated and the PD69101s are reset.

Voltage Regulator

The voltage regulator generates 3.3 VDC and 5 VDC for the internal circuitry. These voltages are derived from the Vmain supply.

CLK

CLK is an internal 8 MHz clock oscillator.

Theory of Operation

The PD69101 performs IEEE802.3af, IEEE802.3at functionality as well as legacy (capacitor) and Cisco's PDs detection, as well as additional protections such as short circuit and dV/dT protection upon startup.

Line Detection

The Line Detection feature detects a valid AF or AT load, as specified in the AF / AT standard. Resistor value should range from 19 kΩ to 26.5 kΩ. Line detection is based on four different voltage levels generated over the PD (the load) as illustrated in Figure 2.

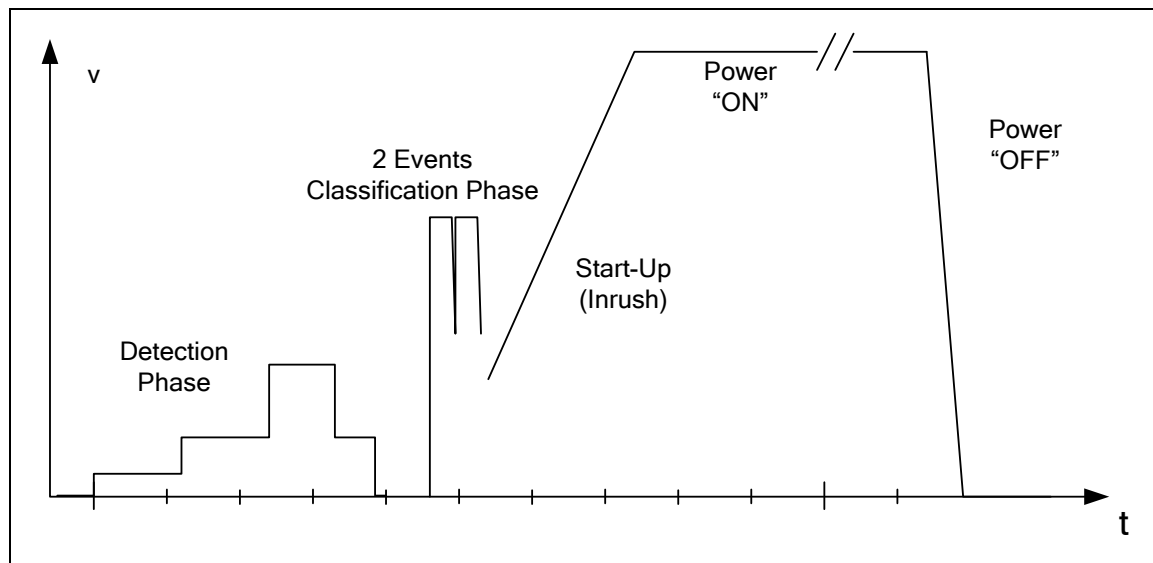


Figure 2: Typical PoE Voltage Time Diagram

Legacy (Cap) Detection

In cases where pin 24 (LEGACY) is set to "0", the PD69101's detection mechanism is configured to detect and power up LEGACY PDs, as well as AF/AT compliant PDs.

This mechanism detects and powers up CISCO Legacy PDs as well.

Classification

The classification process takes place right after the resistor detection, when the resistor detection has completed successfully. The main goal of the classification process is to detect the PD class, as specified in the IEEE802.3AF and AT standards.

In the AF mode the classification mechanism is based on a single voltage level (single finger).

In the AT mode classification mechanism is based on two voltage levels (dual finger) as defined in the IEEE802.3at-2009.

Port Start Up

Upon a successful Detection and Classification process, power is applied to the load via a controlled Start Up mechanism.

During this period current is limited to 425 mA for a typical duration of 65 mS, which enables the PD load to charge and to enter a steady state power condition.

Over-Load Detection and Port Shut Down

After power up, the PD69101 automatically initializes its internal protection mechanisms utilized to monitor and disconnect power from the load in cases where extreme conditions such as over-current or short ports terminals scenario occur, as specified in the IEEE802.3AF/AT standard.

Disconnect Detection

The PD69101 supports DC Disconnect function as per the IEEE802.3AF/AT standard.

This mechanism continuously monitors load current and disconnects power in cases where load current is below 7.5 mA (typ.) for more than 322 mS.

Over-temperature Protection

The PD69101 has internal temperature sensors that continuously monitor junction temperature and disconnect load power when the junction temperature exceeds 200° C. This mechanism protects the device from extreme events, such as high ambient

temperature or other thermo-mechanical failures that may damage the PD69101.

valuable feature which protects the load if the main power source is faulty or damaged.

V_{MAIN} Out of Range Protection

The PD69101 automatically disconnects port power when V_{main} exceeds 60 VDC. This is an extremely

TYPICAL 2 PAIRS APPLICATION

This typical application illustrates a simple “plug and play” Power Over Ethernet solution for a single Ethernet port switch or hub.

“POS” and “NEG” signals should be connected to the switch RJ45 Jack.

AF and AT modes of operations are set through AF/AT and current set pins (DGND or DVDD).

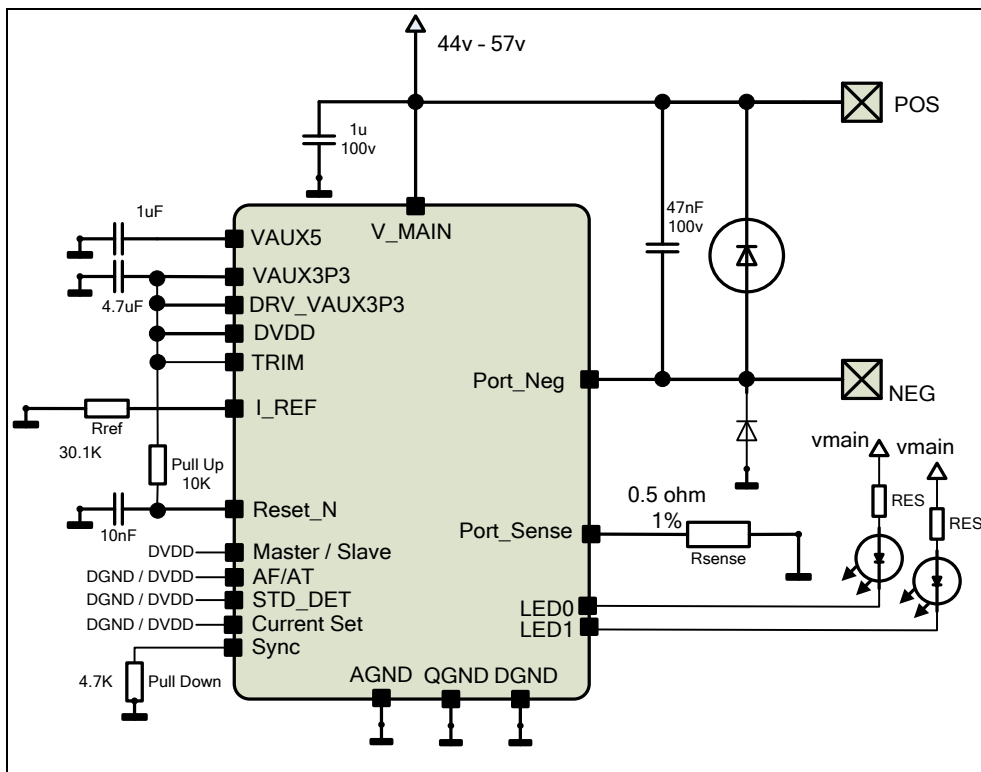


Figure 3: Typical 2 Pair Application

* For detailed application's schematics and layout recommendations, contact sales_AMSG@microsemi.com.

TYPICAL 4 PAIRS APPLICATION

This typical application illustrates a master / slave “plug and play” Power over Ethernet solution for 4 Pairs (data and spare Wires) Ethernet port switch or hub.

“POS” and “NEG” signals are connected to the switch RJ45 jack via line transformers.

AF and AT modes of operations are set through AF/AT and current set pins (DGND or DVDD).

The SYNC pins are used to synchronize the PD69101 Master to the PD69101 Slave so that line detection, classification, power on and power off events are inline with the load.

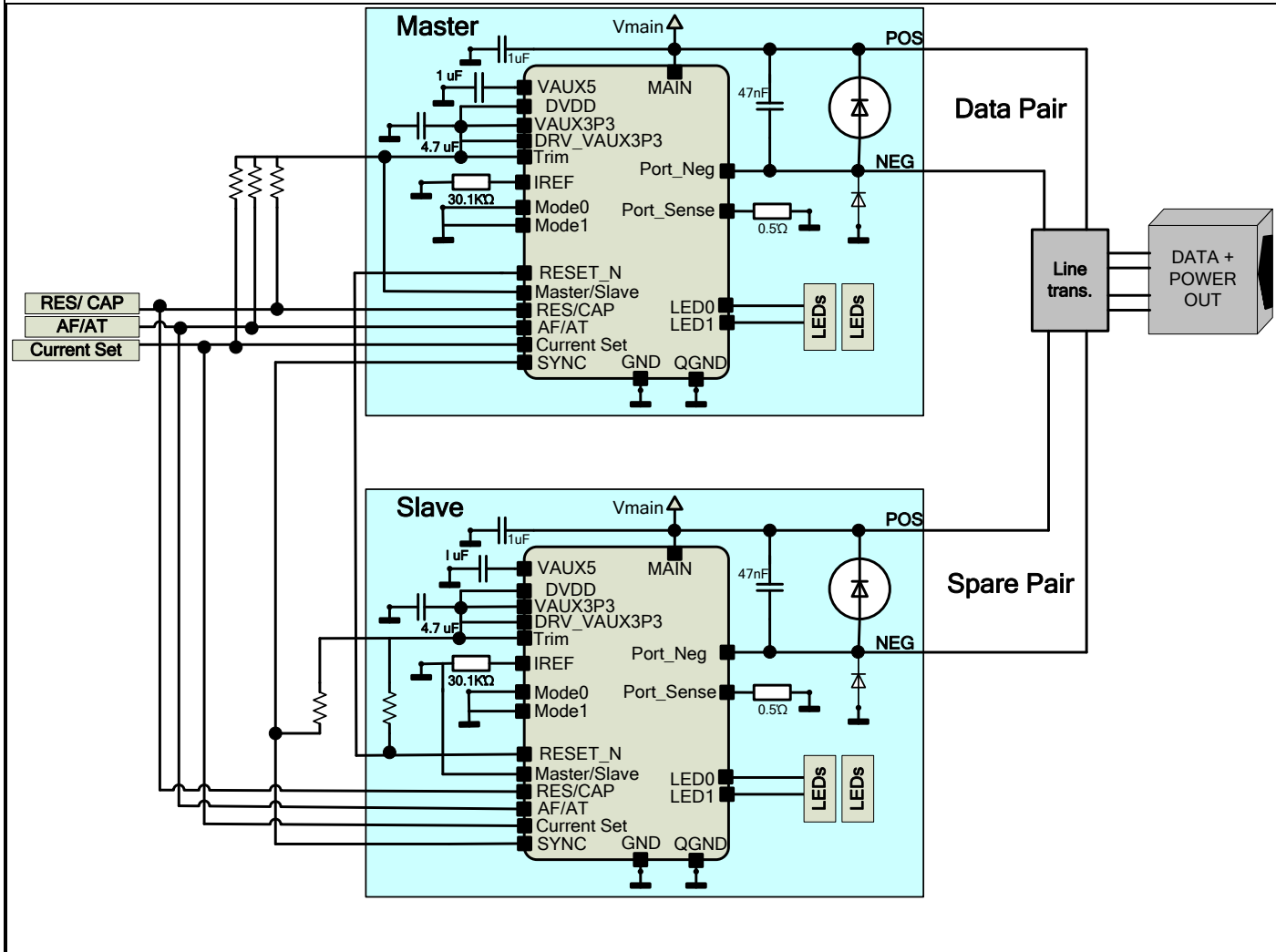


Figure 4: Typical 4 Pair Application

* For detailed application's schematics and layout recommendations, contact sales_AMSG@microsemi.com.

4 PAIR TYPICAL TIMING DIAGRAM

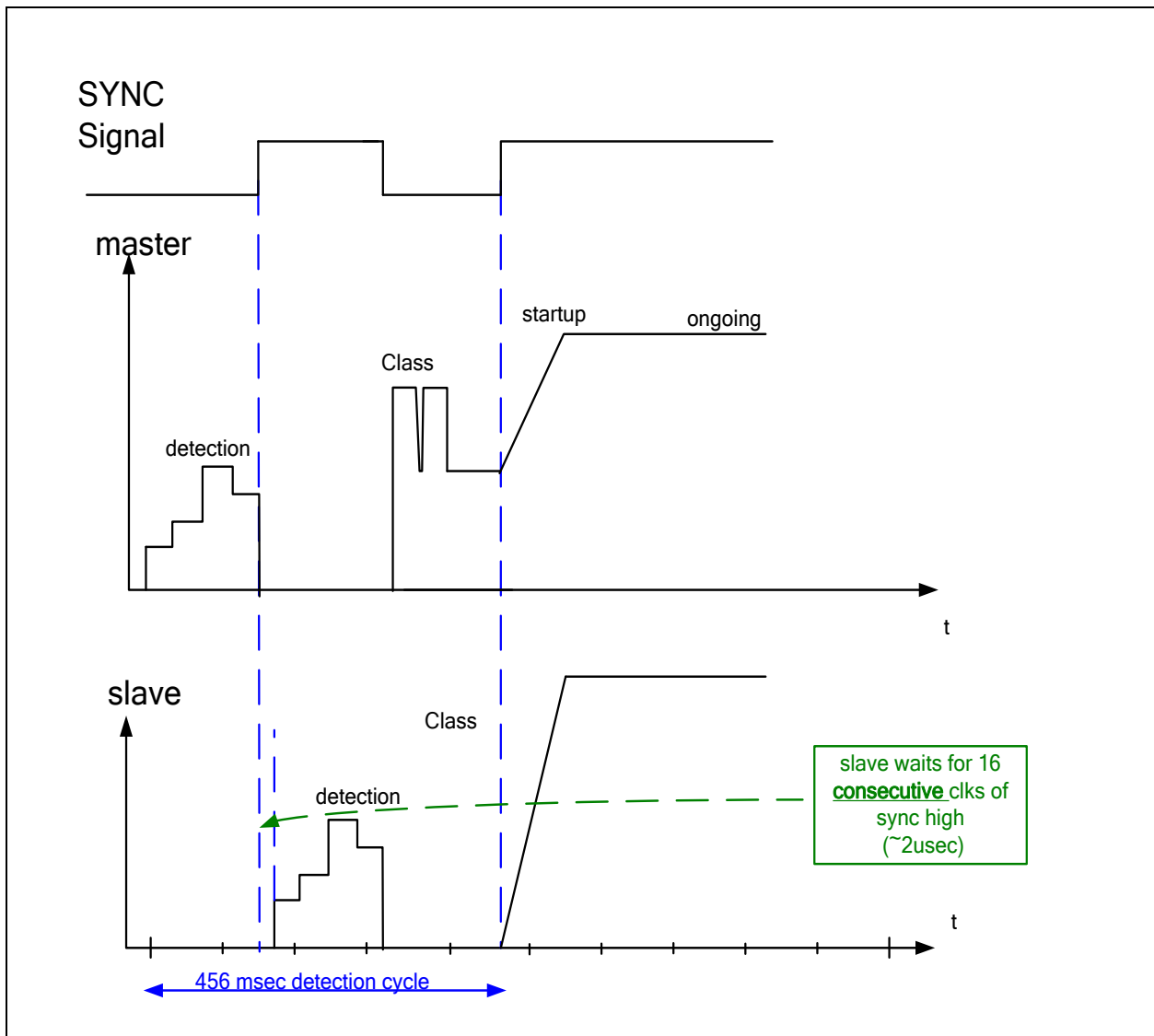


Figure 5: 4 Pair Timing Diagram

Serial Communication - Monitoring Mode

When Mode0 and Mode1 Input pins are configured to Serial Monitoring Mode ("01"), the PD69101 transmits out (continuously and repeatedly) the content of 9 internal registers:

- Data Out Stream is transmitted through LED1 (pin 14)
- Clock Out Stream is transmitted through LED0 (pin 13)
- Data stream is shifted out with a 1 MHz clock (1 µsec).
- Total transaction packet length is 116 µsec.
- The transmission is repeated every 1 msec.
- Between transactions the clock is held low, while data stream out is stable high/low.

Note: To exploit LED1 and LED0 to communicate and monitor transmissions, use a 1 KΩ pull-up resistor to the DVDD.

Table 5: Stream Out Data Transmits 116 bits Starting from MSB to LSB

| MSBYTE | | | | | | | LSBYTE | |
|---|------------|------------|------------|------------|--|---|--|--|
| INTERNAL 0 | INTERNAL 1 | INTERNAL 2 | INTERNAL 3 | INTERNAL 4 | VPORT | VMAIN | IPORT | PORT STATUS |
| 13 BITS | 10 BITS | 23 BITS | 16 BITS | 16 BITS | 10 BITS | 10 BITS | 13 BITS | 5 BITS |
| 78 internal signals used for internal tests | | | | | Port voltage measurement LSB = 58 mV V = Decimal x 58 mV | Vmain voltage measurement LSB = 58 mV V = Decimal x 58 mV | Port current measurement LSB = 238 uA I = Decimal x 238 uA | Real time port status indication See coding table below |

Table 6: Port Status Coding

| BINARY MSB TO LSB | DECIMAL VALUE | DESCRIPTION |
|-------------------|---------------|---------------------------|
| 00000 | 0 | |
| 00001 | 1 | POE idle state |
| 00010 | 2 | |
| 00011 | 3 | Searching phase |
| 00100 | 4 | Res detection phase |
| 00101 | 5 | |
| 00110 | 6 | Back off phase |
| 00111 | 7 | |
| 01000 | 8 | Class phase |
| 01001 | 9 | |
| 01010 | 10 | Wait for start up |
| 01100 | 12 | |
| 01011 | 11 | Cap detection |
| 01101 | 13 | Start up |
| 01110 | 14 | |
| 01111 | 15 | On going |
| 10000 | 16 | |
| 10001 | 17 | UDL |
| 10010 | 18 | Overload or short circuit |
| 10011 | 19 | |
| 10100 | 20 | Vmain out of range |

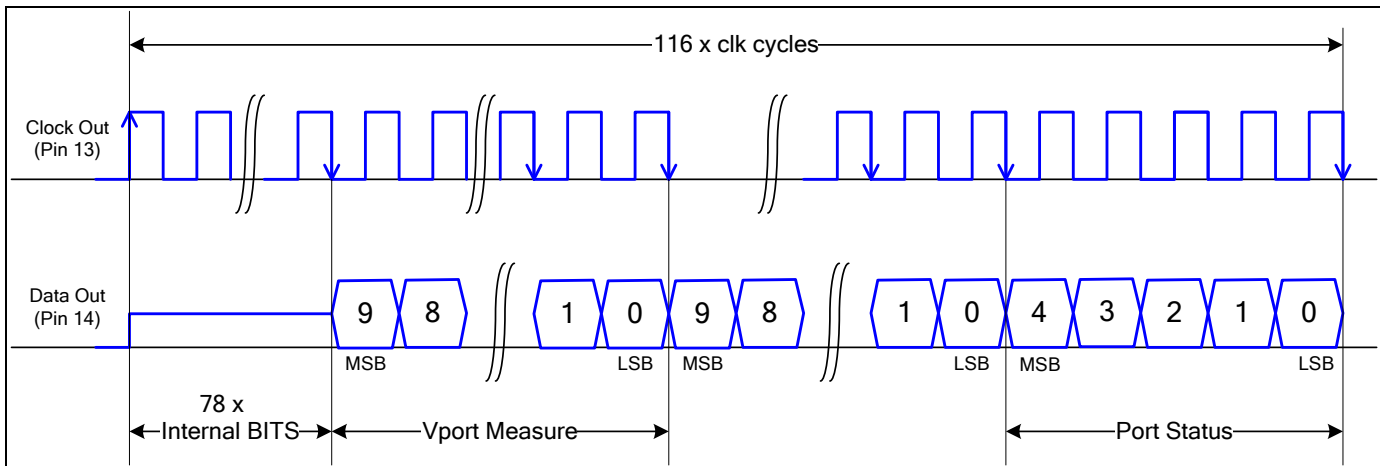


Figure 6: Data Stream Out

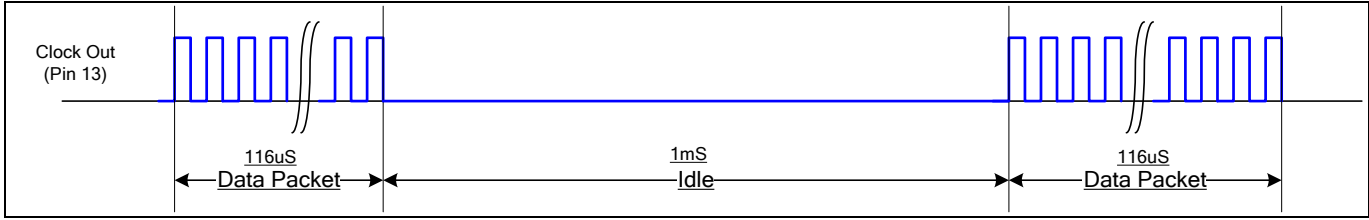


Figure 7: Multi Packet Idle Time (Between Packets)

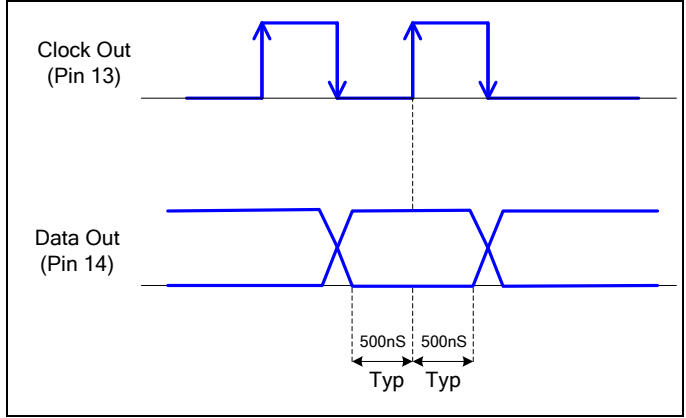


Figure 8: Data / Clock Typical Timing

The information contained in the document (unless it is publicly available on the Web without access restrictions) is PROPRIETARY AND CONFIDENTIAL information of Microsemi and cannot be copied, published, uploaded, posted, transmitted, distributed or disclosed or used without the express duly signed written consent of Microsemi. If the recipient of this document has entered into a disclosure agreement with Microsemi, then the terms of such Agreement will also apply. This document and the information contained herein may not be modified, by any person other than authorized personnel of Microsemi. No license under any patent, copyright, trade secret or other intellectual property right is granted to or conferred upon you by disclosure or delivery of the information, either expressly, by implication, inducement, estoppels or otherwise. Any license under such intellectual property rights must be approved by Microsemi in writing signed by an officer of Microsemi.

Microsemi reserves the right to change the configuration, functionality and performance of its products at anytime without any notice. This product has been subject to limited testing and should not be used in conjunction with life-support or other mission-critical equipment or applications. Microsemi assumes no liability whatsoever, and Microsemi disclaims any express or implied warranty, relating to sale and/or use of Microsemi products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Any performance specifications believed to be reliable but are not verified and customer or user must conduct and complete all performance and other testing of this product as well as any user or customers final application. User or customer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the customer's and user's responsibility to independently determine suitability of any Microsemi product and to test and verify the same. The information contained herein is provided "AS IS, WHERE IS" and with all faults, and the entire risk associated with such information is entirely with the User. Microsemi specifically disclaims any liability of any kind including for consequential, incidental and punitive damages as well as lost profit. The product is subject to other terms and conditions which can be located on the web at <http://www.microsemi.com/legal/tnc.asp>

Revision History

| Revision Level / Date | Para. Affected | Description |
|-----------------------|----------------|--|
| 1.0 / March 2010 | | Official Release |
| 1.1 / March 2010 | | Added wave forms + last functionality update according to evaluation results |
| 1.2 / June 2010 | | Package drawing update |
| 1.3 / June 2010 | | Parameters update |
| 1.4 / Sep 2010 | | Parameters update |
| 1.5 / Dec 2010 | | Parameters update |
| 1.6 / July 2013 | | IC marking update |
| 1.7 / July 2013 | | Add TETA JC data |

© 2010 Microsemi Corp.

All rights reserved.

For support contact: sales_AMSG@microsemi.com

Visit our web site at: www.microsemi.com